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	Filing Date: March 22, 1999	

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Exam. Initial*	Cite No.[1]	U.S. Patent Document Number	Kind Code[2] (If known)	Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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Examiner Signature		Date Considered	09/09/02

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Paper No. 17

Substitute for Form 1449A/PTO (Modified) (use as many sheets as necessary)	Attorney Docket No. 042390P3495C2	Application Number: 09/274,430
Page 11 of 11	First Named Inventor: Michael Barrow	
	Filing Date: March 22, 1999	

OTHER ART – NO PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No[1]	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	Translation[2]
JBV		Philip E. Rogren, "MCM-L Built on Ball Grid Array Formats", Surface Mount International, Proceedings of the Technical Program, San Jose, Ca, August/September 1994	
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		Johnathan L. Houghten, "Plastic Ball-Grid Arrays Continue to Evolve", February 6, 1995 issue of Electronic Design, Vol. 43, No. 3, pgs 5, 7, 141-146, Penton Publishing Inc., Cleveland, OH	
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Examiner Signature	John R. Ugrose	Date Considered	09/06/02

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Paper No. 17

Substitute for Form 1449A/PTO (Modified)

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet	1	of	2

Complete if Known	
Application Number	09/274,430
Filing Date	March 22, 1999
First Named Inventor:	Michel Barrow
Group Art Unit	2841
Examiner Name	~~David A. Foster~~ John Vigushin
Attorney Docket Number	042390P3495C2

U.S. PATENT DOCUMENTS

Exam. Initial*	Cite No.[1]	U.S. Patent Document Number Code[2]	Kind (If known)	Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear

FOREIGN PATENT DOCUMENTS

Exam. Initial*	Cite No.[1]	Foreign Patent Document Office[3]	Number[4]	Kind Code[5] (If known)	Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T[6]

Examiner Signature	John B. Vigushin	Date Considered	09/09/02

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Paper No. 22

Substitute for Form 1449A/PTO (Modified)	Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT *(use as many sheets as necessary)*	Application Number	09/274,430
	Filing Date	March 22, 1999
	First Named Inventor:	Michael Barrow
	Group Art Unit	2841
	Examiner Name	~~David A. Foster~~ John Vigushin
Sheet 2 of 2	Attorney Docket Number	042390P3495C2

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OTHER ART – NO PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No[1]	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T[2]
JBV		Bruce Freyman et al. "Surface Mount Process Technology for Ball Grid Array Packaging", Surface Mount International, August 29-September 2, 1993, Amkor Electronics Inc., San Jose, California, pgs 81-85	
JBV		Johnathan L. Houghten "Plastic Ball-Grid Arrays Continue to Evolve", Electronic Design Magazine, February 6, 1995, pgs 141-146, Vol. 43, No. 3, Penton Publishing	
JBV		LSI Logic Corporation, Package Selector Guide 1994-1995, Second Edition, Milpitas, California	
JBV		LSI Logic Corporation, Package Selector Guide 1994-1995 Errata	
JBV		Semiconductor Group Package Outlines Reference Guide, Texas Instruments Incorporated, Plastic Ball Grid Array Drawings, 1995	

Examiner Signature	John B. Vigushin	Date Considered	09/09/02

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